

GP ~~2936~~
2836



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Title: PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES

Docket No.: 303.603US1

Serial No.: 09/382,929

Filed: August 25, 1999

Due Date: January 25, 2000

Examiner:

Group Art Unit: 2936

Assistant Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

- X A return postcard.
- X An Information Disclosure Statement (1 pgs.), Form 1449 (1 pgs.), and copies of 9 cited references.
- X A Communication Concerning Co-Pending Applications (1 pg.).

Please consider this a **PETITION FOR EXTENSION OF TIME** for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this Transmittal Letter and the paper, as described above, are being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on this 3rd day of January, 2000.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Danny J. Padya
Atty: Danny J. Padya
Reg. No. 35,635

Customer Number **21186**

(GENERAL)

RECEIVED

JAN 10 2000

TECHNOLOGY CENTER 2800

S/N 09/382,929

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Serial No.: 09/382,929

Filed: August 25, 1999

Title:

PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES

Examiner:

Group Art Unit: 2936

Docket: 303.603US1

Assistant Commissioner for Patents
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant further requests that a copy of the 1449 form, initialed by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Under 37 C.F.R. §1.97(b)(3), it is believed that no fee or certificate is required with this Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

PAUL A. FARRAR

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2109

Date January 3, 2000

By Danny J. Padys
Danny J. Padys
Reg. No. 35,635

RECEIVED

JAN 10 2000

TECHNOLOGY CENTER 2800

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231 on January 25, 2000.

Gina Borre
Name

Gina Bone
Signature

S/N 09/382,929

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner:

Serial No.: 09/382,929

Group Art Unit: 2936

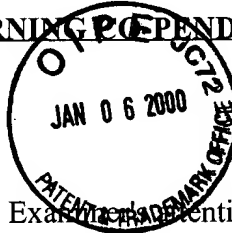
Filed: August 25, 1999

Docket: 303.603US1

Title: PACKAGING OF ELECTRONIC CHIPS WITH AIR-BRIDGE STRUCTURES

COMMUNICATION CONCERNING PENDING APPLICATION(S)

Assistant Commissioner for Patents
Washington, D.C. 20231



Applicant would like to bring to the Examiner's attention the following related co-pending application(s) in the above-identified patent application:

<u>Serial No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/382,524	08/25/1999	00303.610US1	INSULATORS FOR HIGH DENSITY CIRCUITS

Respectfully submitted,

PAUL A. FARRAR

By Applicant's Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 371-2109

Date January 3, 2000 By Danny J. Pady
Danny J. Pady
Reg. No. 35,635

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Assistant Commissioner of Patents, Washington, D.C. 20231 on January 3, 2000.

CINA Borre
Name

Gina Bone
Signature

RECEIVED

JAN 10 2000

TECHNOLOGY CENTER 2800